Company Contact: Justin Moll , Pixus Technologies Justin.moll@pixustechnologies.com 519-885-5775

New Development Chassis From Pixus Technologies Supports Dual Board Depths, SpaceVPX

Waterloo, Ontario — June 22, 2020 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers an OpenVPX chassis platform that supports both 160mm deep (standard OpenVPX) and 220mm deep (SpaceVPX™) boards.

The open frame chassis features up to four slots at 1.0" pitch of each board depth type. The modular enclosure allows various board pitches to be utilized at 0.2" increments. Card guides to support both air-cooled boards and conduction-cooled boards are standard. There are also 220mm deep card guides that are wider to support extra thick SpaceVPX conduction-cooled boards per VITA 78.

Pixus offers a wide range of 3U or 6U OpenVPX backplanes, including versions that utilize the ultra rugged KVPX connector per VITA 63. The chassis includes an optional modular 600W or 1200W power supply for up to 6 VPX voltages. Power interface boards per VITA 62 are also an option.

Pixus offers backplanes, chassis platforms, and specialty products in various modular open standard architectures. The company provides enclosure solutions in 19" rackmount, ATR/ Rugged, development, and specialty small form factor designs.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs.   Pixus also has an extensive offering of VME-based and cPCI-based solutions.   In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.